Low-Voltage CMOS Quad 2-Input Multiplexer

With 5 V-Tolerant Inputs (Inverting)

The MC74LCX158 is a high performance, quad 2–input inverting multiplexer operating from a 2.3 to 3.6 V supply. High impedance TTL compatible inputs significantly reduce current loading to input drivers while TTL compatible outputs offer improved switching noise performance. A V_I specification of 5.5 V allows MC74LCX158 inputs to be safely driven from 5 V devices.

Four bits of data from two sources can be selected using the Select and Enable inputs. The four outputs present the selected data in the inverted form. The MC74LCX158 can also be used as a function generator. Current drive capability is 24 mA at the outputs.

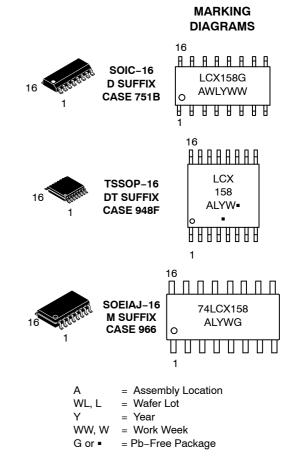
Features

- $\bullet\,$ Designed for 2.3 to 3.6 V V_{CC} Operation
- 5 V Tolerant Inputs Interface Capability With 5 V TTL Logic
- LVTTL Compatible
- LVCMOS Compatible
- 24 mA Balanced Output Sink and Source Capability
- Near Zero Static Supply Current (10 µA) Substantially Reduces System Power Requirements
- Latchup Performance Exceeds 500 mA
- ESD Performance:
 - Human Body Model >2000 V
 - ♦ Machine Model >200 V
- These Devices are Pb-Free and are RoHS Compliant



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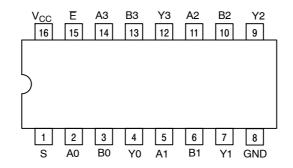
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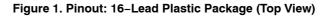


(Note: Microdot may be in either location)

ORDERING INFORMATION

See detailed ordering and shipping information in the package dimensions section on page 3 of this data sheet.





PIN NAMES

Pins	Function
An	Source 0 Data Inputs
Bn	Source 1 Data Inputs
Ē	Enable Input
S	Select Input
Yn	Outputs

TRUTH TABLE

Inp	outs	Outputs
Output Enable	Select	Y0-Y3
Н	Х	Н
L	L	A0-A3
L	Н	B0-B3

X = Don't Care

A0–A3, B0–B3 = The levels of the respective Data–Word Inputs

PIN DESCRIPTIONS

OUTPUTS

A0-A3 (Pins 2, 5, 11, 14)

INPUTS

Nibble A inputs. The data present on these pins is transferred to the outputs when the Select input is at a low level and the Output Enable input is at a low level. The data is presented to the outputs in inverted form for the LCX158.

B0-B3 (Pins 3, 6, 10, 13)

Nibble B inputs. The data present on these pins is transferred to the outputs when the Select input is at a high level and the Output Enable input is at a low level. The data is presented to the outputs in inverted form for the LCX158.

Y0-Y3 (Pins 4, 7, 9, 12)

Data outputs. The selected input nibble is presented at these outputs when the Output Enable input is at a low level. The data present on these pins is in its inverted form for the LCX158. For the Output Enable input at a high level, the outputs are at a high level for the LCX158.

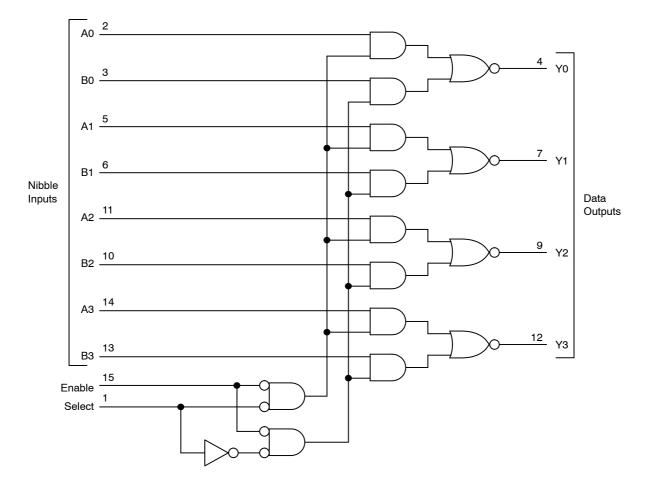
Select (Pin 1)

Nibble select. This input determines the data word to be transferred to the outputs. A low level on this input selects the A inputs and a high level selects the B inputs.

CONTROL INPUTS

Enable (Pin 15)

Output Enable input. A low level on this input allows the selected data to be presented at the outputs. A high level on this input sets all of the outputs to a high level for the LCX158.





ORDERING INFORMATION

Device	Package	Shipping [†]
MC74LCX158DG	SOIC-16 (Pb-Free)	48 Units / Rail
MC74LCX158DR2G	SOIC-16 (Pb-Free)	2500 Tape & Reel
MC74LCX158DTG	TSSOP-16*	96 Units / Rail
MC74LCX158DTR2G	TSSOP-16*	2500 Tape & Reel
MC74LCX158MG	SOEIAJ-16 (Pb-Free)	50 Units / Rail

†For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

*This package is inherently Pb-Free.

MAXIMUM RATINGS

Symbol	Parameter	Condition	Value	Units
V _{CC}	DC Supply Voltage		-0.5 to +7.0	V
VI	DC Input Voltage		$-0.5 \leq V_I \leq +7.0$	V
Vo	DC Output Voltage	Output in HIGH or LOW State (Note 1)	$-0.5 \leq V_O \leq V_{CC} + 0.5$	V
I _{IK}	DC Input Diode Current	V _I < GND	-50	mA
I _{OK}	DC Output Diode Current	V _O < GND	-50	mA
		V _O > V _{CC}	+50	mA
Ι _Ο	DC Output Source/Sink Current		±50	mA
I _{CC}	DC Supply Current Per Supply Pin		±100	mA
I _{GND}	DC Ground Current Per Ground Pin		±100	mA
T _{STG}	Storage Temperature Range		–65 to +150	°C

Maximum ratings are those values beyond which device damage can occur. Maximum ratings applied to the device are individual stress limit values (not normal operating conditions) and are not valid simultaneously. If these limits are exceeded, device functional operation is not implied, damage may occur and reliability may be affected. 1. I_O absolute maximum rating must be observed.

RECOMMENDED OPERATING CONDITIONS

Symbol	Parameter	Min	Тур	Max	Units
V _{CC}	Supply Voltage Operating Data Retention Only	2.0 1.5	2.3 to 3.3	3.6 3.6	V
VI	Input Voltage	0		5.5	V
V _O	Output Voltage (HIGH or LOW State) (3-State)	0		V _{CC}	V
I _{OH}				-24 -12 -8	mA
I _{OL}				+24 +12 +8	mA
T _A	Operating Free-Air Temperature	-40		+85	°C
$\Delta t/\Delta V$	Input Transition Rise or Fall Rate, V _{IN} from 0.8 V to 2.0 V, V _{CC} = 3.0 V	0		10	ns/V

			T _A = −40°C to +85°C		
Symbol	Characteristic	Condition	Min	Мах	Units
VIH	Minimum HIGH Level Input Voltage (Note 2)	$2.3~V \leq V_{CC} \leq 2.7~V$	1.7		V
		$2.7~V \leq V_{CC} \leq 3.0~V$	2.0		
		$3.0~V \leq V_{CC} \leq 3.6~V$	2.0		
VIL	Maximum LOW Level Input Voltage (Note 2)	$2.3 \text{ V} \le \text{V}_{CC} \le 2.7 \text{ V}$		0.7	V
		$2.7~V \leq V_{CC} \leq 3.0~V$		0.8	
		$3.0~V \leq V_{CC} \leq 3.6~V$		0.8	
V _{OH}	Minimum HIGH Level Output Voltage	$2.3 \text{ V} \le \text{V}_{CC} \le 3.6 \text{ V}; \text{ I}_{OH} = -100 \mu\text{A}$	V _{CC} – 0.2		V
		V _{CC} = 2.3 V; I _{OH} = -8 mA	1.7		
		V _{CC} = 2.7 V; I _{OH} = -12 mA	2.2		
		V _{CC} = 3.0 V; I _{OH} = -18 mA	2.4		
		$V_{CC} = 3.0 \text{ V}; \text{ I}_{OH} = -24 \text{ mA}$	2.2		
V _{OL}	Maximum LOW Level Output Voltage	2.3 V \leq V_{CC} \leq 3.6 V; I_{OH} = 100 μA		0.2	V
		V _{CC} = 2.3 V; I _{OH} = 8 mA		0.7	
		V _{CC} = 2.7 V; I _{OH} = 12 mA		0.4	
		V _{CC} = 3.0 V; I _{OH} = 16 mA		0.4	
		V _{CC} = 3.0 V; I _{OH} = 24 mA		0.55	
I	Input Leakage Current	$2.3 \text{ V} \leq \text{V}_{CC} \leq 3.6 \text{ V}; \text{ 0 V} \leq \text{V}_{I} \leq 5.5 \text{ V}$		±5.0	μA
I _{CC}	Quiescent Supply Current	2.3 V \leq V_{CC} \leq 3.6 V; V_{I} = V_{CC} or GND		10	μΑ
		$2.3~V \leq V_{CC} \leq 3.6~V;~3.6~V \leq V_I \leq 5.5~V$		±10	
ΔI_{CC}	Increase in I _{CC} per Input	$2.3~V \leq V_{CC} \leq 3.6~V;~V_{IH}$ = V_{CC} – $0.6~V$		500	μA

DC ELECTRICAL CHARACTERISTICS

2. These values of V_I are used to test DC electrical characteristics only.

AC CHARACTERISTICS

				Lin	nits			
				T _A = -40°C	C to +85°C			
		V _{CC} = 3.0	$V \pm$ 3.6 V	V _{CC} =	2.7 V	V _{CC} = 2.3	V to 2.7 V	
		C _L =	50 pF	C _L = 5	50 pF	C _L =	30 pF	
Symbol	Parameter	Min	Max	Min	Max	Min	Max	Units
t _{PLH}	Propagation Delay	1.0	6.5	1.0	7.5	1.0	8.5	ns
t _{PHL}	A or B to Y	1.0	6.5	1.0	7.5	1.0	8.5	
t _{PLH}	Propagation Delay	1.0	7.0	1.0	8.0	1.0	9.0	ns
t _{PHL}	S to Y	1.0	7.0	1.0	8.0	1.0	9.0	
t _{PLH}	Propagation Delay	1.0	7.0	1.0	8.0	1.0	9.0	ns
t _{PHL}	Output Enable to Y	1.0	7.0	1.0	8.0	1.0	9.0	
t _{OSHL}	Output-to-Output Skew		1.0					ns
t _{OSLH}			1.0					

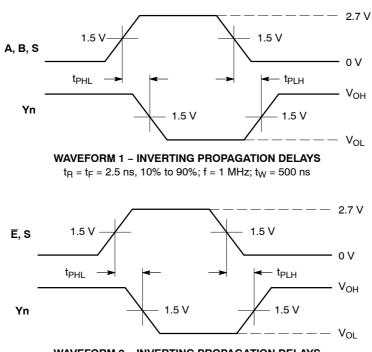
DYNAMIC SWITCHING CHARACTERISTICS

			T,	A = +25°	С	
Symbol	Characteristic	Condition	Min	Тур	Max	Units
V _{OLP}	Dynamic LOW Peak Voltage (Note 3)	V_{CC} = 3.3 V, C_L = 50 pF, V_{IH} = 3.3 V, V_{IL} = 0 V		0.8		V
V _{OLV}	Dynamic LOW Valley Voltage (Note 3)	V_{CC} = 3.3 V, C_{L} = 50 pF, V_{IH} = 3.3 V, V_{IL} = 0 V		0.8		V

3. Number of outputs defined as "n". Measured with "n-1" outputs switching from HIGH-to-LOW or LOW-to-HIGH. The remaining output is measured in the LOW state.

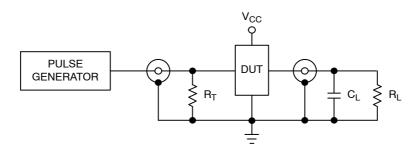
CAPACITIVE CHARACTERISTICS

Symbol	Parameter	Condition	Typical	Units
C _{IN}	Input Capacitance	V_{CC} = 3.3 V, V_{I} = 0 V or V_{CC}	7	pF
C _{OUT}	Output Capacitance	V_{CC} = 3.3 V, V_{I} = 0 V or V_{CC}	8	pF
C _{PD}	Power Dissipation Capacitance	10 MHz, V_{CC} = 3.3 V, V_{I} = 0 V or V_{CC}	25	pF



WAVEFORM 2 – INVERTING PROPAGATION DELAYS $t_R = t_F = 2.5 \text{ ns}, 10\% \text{ to } 90\%; \text{ f} = 1 \text{ MHz}; t_W = 500 \text{ ns}$





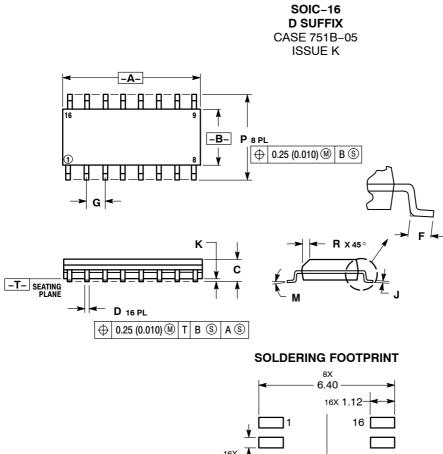
 $C_L = 50 \text{ pF}$ or equivalent (Includes jig and probe capacitance)

 $R_L = R_1 = 500 \Omega$ or equivalent

 $R_T = Z_{OUT}$ of pulse generator (typically 50 Ω)



PACKAGE DIMENSIONS



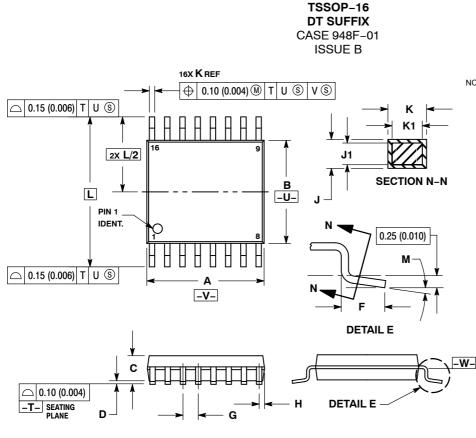
- NOTES:
 DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
 CONTROLLING DIMENSION: MILLIMETER.
 DIMENSIONS A AND B DO NOT INCLUDE MOLD PROTRUSION.
 MAXIMUM MOLD PROTRUSION 0.15 (0.006) PER SIDE.
 DIMENSION DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE DAMBAR PROTRUSION SHALL BE 0.127 (0.005) TOTAL IN EXCESS OF THE D DIMENSION AT MAXIMUM MATERIAL CONDITION. MAXIMUM MATERIAL CONDITION.

	MILLIN	IETERS	INC	HES
DIM	MIN	MAX	MIN	MAX
Α	9.80	10.00	0.386	0.393
В	3.80	4.00	0.150	0.157
С	1.35	1.75	0.054	0.068
D	0.35	0.49	0.014	0.019
F	0.40	1.25	0.016	0.049
G	1.27	BSC	0.050	BSC
J	0.19	0.25	0.008	0.009
K	0.10	0.25	0.004	0.009
М	0 °	7°	0 °	7°
Ρ	5.80	6.20	0.229	0.244
R	0.25	0.50	0.010	0.019

16X 0.58 ∟1.27 <u>↓</u> РІТСН 8 9

DIMENSIONS: MILLIMETERS

PACKAGE DIMENSIONS



NOTES: 1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982. 2. CONTROLLING DIMENSION: MILLIMETER.

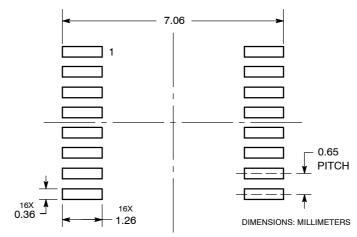
DIMENSION A DOES NOT INCLUDE MOLD FLASH. PROTRUSIONS OR GATE BURRS. MOLD FLASH OR GATE BURRS. SHALL NOT EXCEED 0.15 (0.006) PER SIDE.

 DIMENSION B DOES NOT INCLUDE INTERLEAD FLASH OR PROTRUSION. INTERLEAD FLASH OR PROTRUSION. INTERLEAD FLASH OR PROTRUSION SHALL NOT EXCEED 0.25 (0.010) PER SIDE. 5. DIMENSION K DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE DAMBAR PROTRUSION SHALL BE 0.08 (0.003) TOTAL IN EXCESS OF THE K DIMENSION AT MAXIMUM MATERIAL CONDITION CONDITION. 6. TERMINAL NUMBERS ARE SHOWN FOR

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 REFERENCE ONLY.
 DIMENSION A AND B ARE TO BE DETERMINED AT DATUM PLANE -W-

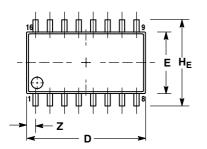
	MILLIN	IETERS	INC	HES
DIM	MIN	MAX	MIN	MAX
Α	4.90	5.10	0.193	0.200
В	4.30	4.50	0.169	0.177
С		1.20		0.047
D	0.05	0.15	0.002	0.006
F	0.50	0.75	0.020	0.030
G	0.65	BSC	0.026 BSC	
Н	0.18	0.28	0.007	0.011
J	0.09	0.20	0.004	0.008
J1	0.09	0.16	0.004	0.006
Κ	0.19	0.30	0.007	0.012
K1	0.19	0.25	0.007	0.010
L	6.40 BSC		0.252	2 BSC
м	0 °	8°	0 °	8 °

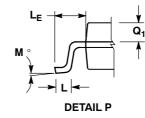
SOLDERING FOOTPRINT

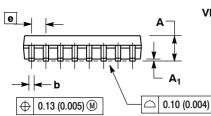


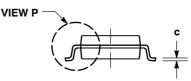
PACKAGE DIMENSIONS

SOEIAJ-16 **M SUFFIX** CASE 966-01 **ISSUE A**









NOTES:

1. DIMENSIC Y14.5M, 1982. DIMENSIONING AND TOLERANCING PER ANSI

2. CONTROLLING DIMENSION: MILLIMETER. 3. DIMENSIONS D AND E DO NOT INCLUDE MOLD FLASH OR PROTRUSIONS AND ARE MEASURED AT THE PARTING LINE. MOLD FLASH OD PROTRUCING WILL NUMBER GLASH

OR PROTRUSIONS SHALL NOT EXCEED 0.15 (0.006) PER SIDE.

(0.000) PER SIDE. 4. TERMINAL NUMBERS ARE SHOWN FOR REFERENCE ONLY. 5. THE LEAD WIDTH DIMENSION (b) DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE DAMBAR PROTRUSION SHALL BE 0.08 (0.003) TOTAL IN EXCESS OF THE LEAD WIDTH DIMENSION AT MAXIMUM MATERIAL CONDITION. DAMBAR CANNOT BE LOCATED ON THE LOWER RADIUS OR THE FOOT. MINIMUM SPACE BETWEEN PROTRUSIONS AND ADJACENT LEAD TO BE 0.46 (0.018).

	MILLIN	IETERS	INC	HES
DIM	MIN	MAX	MIN	MAX
Α		2.05		0.081
A ₁	0.05	0.20	0.002	0.008
b	0.35	0.50	0.014	0.020
C	0.10	0.20	0.007	0.011
D	9.90	10.50	0.390	0.413
E	5.10	5.45	0.201	0.215
е	1.27 BSC		0.050) BSC
HE	7.40	8.20	0.291	0.323
L	0.50	0.85	0.020	0.033
LE	1.10	1.50	0.043	0.059
Μ	0 °	10 °	0 °	10 °
Q ₁	0.70	0.90	0.028	0.035
Z		0.78		0.031

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